



#### Features:

- NVIDIA® Jetson AGX Orin, up to 275TOPS
- 2\*GbE, 1\*10GbE RJ45
- 8\*GMSL2 camera ports, supports GNSS time synchronization
- 3\*USB 10Gbps, 1\*USB 5Gbps Type-A
- 2\*RS232/RS485, 2\*CAN FD, 8\*GPIO
- Wi-Fi, BT, 4G/5G
- Active Heat Dissipation
- 12~28V DC



Remote Management



Condition Monitoring



Remote Operation And Maintenance



Safety Control

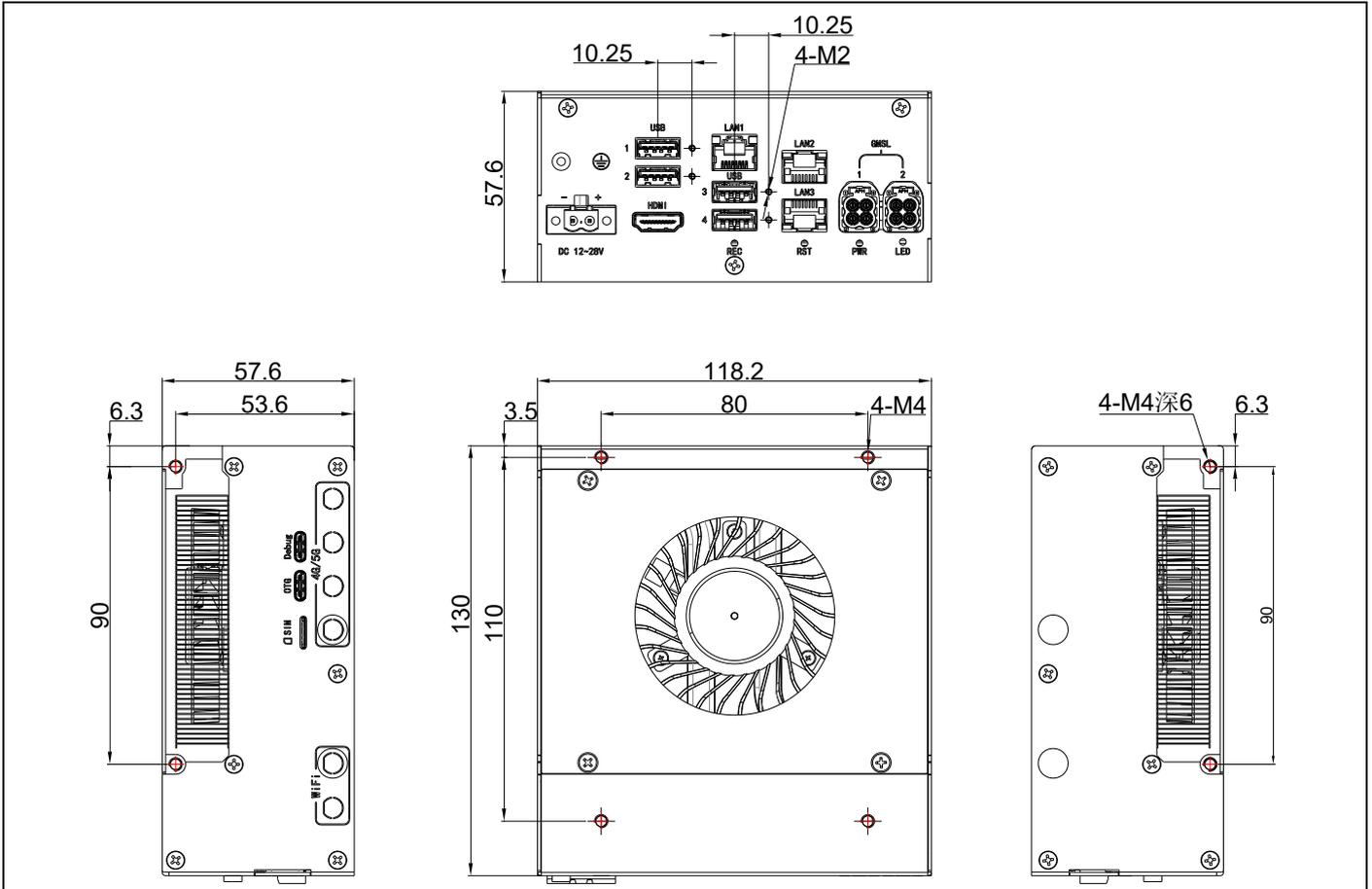
## Product Specification

Model		TER30J-C3	
<b>Core Modules</b>		Jetson AGX Orin 32GB, 200 TOPS   Jetson AGX Orin 64GB, 275 TOPS	
<b>Ethernet</b>	Controller	1 * Marvell® AQR113C, 10/100/1000/2500/5000/10000 Mbps 3 * Intel® i210AT, 10/100/1000 Mbps	
	Storage	1 * M.2 Key-M Slot (NVMe SSD, 2280)	
<b>Expansion Slots</b>	M.2	1 * M.2 Key-B Slot (USB 5Gbps + USB 2.0, 3052, with 1 * Nano SIM Card Slot) 1 * M.2 Key-E Slot (PCIe x1 + USB 2.0)	
	<b>Front I/O</b>	Ethernet	1 * 10GbE (RJ45) 2 * GbE (RJ45)
USB		3 * USB 10Gbps (Type-A) 1 * USB 5Gbps (Type-A)	
Display		1 * HDMI: Resolution up to 4096*2304@30Hz (Type-A)	
GMSL		8 * GMSL2 (FAKRA Mini Quad, Male)	
LED		1 * System Status LED	
Button			1 * Power Button 1 * System Reset button 1 * System Recovery button
		Power Input	1 * Power Input (2P, P=5.00/5.08, Terminal Block)
<b>Side I/O</b>	OTG	1 * USB 2.0 (Type-C, Flashing port)	
	Debug	1 * USB 2.0 (Type-C, Debug port)	
	SIM	1 * Nano SIM Card Slots	
<b>Internal I/O</b>	Front Panel	1 * Front Panel (Power + Reset + Recovery, wafer)	
	Docking	Ethernet (i210-AT) + Debug (Uart) + OTG (USB 2.0) + GPIO	
	FAN	1 * System Fan (wafer)	
	GPIO	8bit GPIO (OS Configurable DI/DO and H/L, wafer)	
	Serial	2 * RS232/485 (OS Configurable, wafer) 1 * TTL (wafer)	
	PPS	1 * PPS IN (wafer)	
	Audio	1 * Audio (Line_Out + Mic) (wafer)	
<b>Power Supply</b>	Type	AT/ATX	
	Power Input Voltage	12 ~ 28V DC	
	Connector	1 * Power Input Connector (2P, P=5.08mm, Terminal Block)	
<b>OS Support</b>	RTC Battery	CR2032 Coin Cell	
	Linux	Jetpack6.2 (Ubuntu22.04)	
<b>Mechanical</b>	Enclosure Material	Aluminum alloy	
	Dimensions	118.2mm(L) * 130mm(W) * 57.6mm(H)	
	Mounting	Bracket Mounting	
<b>Environment</b>	Heat Dissipation System	Active Fan Cooling	
	Operating Temperature	-20~50°C (Industrial SSD)	
	Storage Temperature	-40~80°C (Industrial SSD)	



Relative Humidity	10 to 95% RH (non-condensing)
Vibration During Operation	3Grms@5-500Hz, random, 1hr/axis
Shock During Operation	15G, half sine, 11ms, ±X/Y/Z, 3 shocks/axis

## Product Size



## Product I/O

